



Light Emitters

Device Type	Power Output		VF		λ_p		Key Features
	min. mW	@ IF mA	typ	max. V	@ IF mA	typ μm	
TIL23	0.4	50	35°	1.5	50	0.93	} Pill package for mounting on double-sided printed circuit board
TIL24	1.0	50	35°	1.5	50	0.93	
TIL25	0.7	50	35°	1.5	50	0.94	
TIL31	3.3	100	10°	1.75	100	0.94	} Hermetically sealed TO18 package
TIL33	2.5	100	80°	1.75	100	0.94	
TIL34	1.6	100	10°	1.75	100	0.94	
TIL32	0.5	20	35°	1.6	20	0.94	Low cost plastic package

Source and Sensor Assemblies

Device Type	Type	On-state Collector Current			Off-state Collector Current		Key Features
		min. IC(on) mA	" IF mA	" VCE V	max. IC(off) nA	" VCE V	
TIL138	One-channel transmissive assembly	1.6	35	0.5	25	30	} A TIL32 gallium arsenide IRED and a TIL78 phototransistor mounted in a plastic housing
TIL139	One-channel reflective assembly	0.4	15	0.5	—	—	
TIL143	One-channel transmissive assembly	10 μA	40	5	25	30	} Standard dual-in-line spacing
TIL144	One-channel transmissive assembly	200 μA	20	10	100	10	
TIL145	One-channel transmissive assembly	50 μA	20	10	100	10	} High-gain darlington phototransistor
TIL146	One-channel transmissive assembly	2	16	1	100	5	
TIL147	One-channel transmissive assembly	1.6	50	1	100	5	} Standard dual-in-line pin spacing
TIL148	One-channel transmissive assembly	4	20	5	100	10	
		1	20	5	100	10	